



MICROPOSIT™ EC SOLVENT 11

For Ancillaries Applications

DESCRIPTION

MICROPOSIT™ EC Solvent 11 is engineered to eliminate the photoresist edge bead that occurs during typical spin coat wafer processing.

Removing the edge bead immediately after photoresist coating reduces particulate associated defects caused by subsequent wafer processing.

MICROPOSIT EC Solvent 11 can also be used to clean and purge photoresist dispense lines and spinner cup bowls.

ADVANTAGES

- Toxicologically safer alternative to the ethylene glycol derived ether acetates
- Compatible with all MICROPOSIT and MEGAPOSIT™ Photoresists
- Efficient and expedient removal of photoresist edge bead
- Low metal ion content

PROPERTIES

MICROPOSIT EC Solvent 11 undergoes quality testing to assure maximum lot-to-lot reproducibility. The final product is filtered to 0.2 µm absolute directly into pre-cleaned containers. A dated batch code is included on each bottle.

INSTRUCTIONS FOR USE

MICROPOSIT EC Solvent 11 is a ready-to-use product.

Edge bead removal (EBR) is an equipment dependent process. Exact application programs (spin speeds and times) depend on wafer size, nozzle placement, spray pressure, amount of edge bead, exhaust flow, wafer bevel and resist solubility. Uniform and repeatable EBR using a GCA 1006 WAFERTRAC™ has been attained with the process steps shown below.

TECHNICAL LITERATURE

Please Contact your Technical Sales Representative for information on the use and performance of Rohm and Haas Electronic Materials products.

PROCESS STEPS

1. Decelerate spin speed to 800 rpm and stabilize spin speed for 2 seconds directly after photoresist application and final spin to nominal thickness.
2. Turn backside EBR dispense on (3 psi) while spinning at 800 rpm for 3 seconds.
3. Accelerate spin speed at 6,000 rpm/sec. to 1,000 rpm for 10 additional seconds of EBR dispense.
4. Turn backside EBR dispense off.
5. Accelerate at 1,000 rpm/sec. to 2,500 rpm.
6. Spin at 2,500 rpm for 12 seconds.
7. End process.

EQUIPMENT

MICROPOSIT EC Solvent 11 can be used on coating equipment with edge bead removal processing capability. Compatible materials include stainless steel, glass, ceramic, polypropylene, high-density polyethylene, polytetrafluoroethylene or equivalent materials.

HANDLING PRECAUTIONS

Before using this product, consult the Material Safety Data Sheet for details on product hazards, recommended handling precautions and product storage.

CAUTION! Keep combustible and/or flammable products and their vapors away from heat, sparks, flames and other sources of ignition including static discharge. Processing or operating at temperatures near or above product flashpoint may pose a fire hazard. Use appropriate grounding and bonding techniques to manage static discharge hazards.

STORAGE

Store products in tightly closed original containers at temperatures recommended on the product label.

DISPOSAL CONSIDERATIONS

Dispose in accordance with all local, state (provincial) and federal regulations. Empty containers may contain hazardous residues. This material and its container must be disposed in a safe and legal manner.

MICROSOFT EC SOLVENT II



ELECTRONIC MATERIALS



Circuit Board Technologies



CMP Technologies



Microelectronic Technologies



Packaging and Finishing Technologies

For locations and information please visit; <http://electronicmaterials.rohmhaas.com>

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